**Features**

- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability

Typical Applications

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-252
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked

■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	MBR10100CD	MBR10150CD	MBR10200CD
Device marking code			MBR10100CD	MBR10150CD	MBR10200CD
Repetitive Peak Reverse Voltage	VRRM	V	100	150	200
Average Rectified Output Current @60Hz sine wave, R-load, Ta=25°C	Io	A		10	
Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, Ta=25°C	Ifsm	A		120	
Current Squared Time @1ms≤t<8.3ms Tj=25°C,	I²t	A²s		60	
Storage Temperature	Tstg	°C		-55 ~ +175	
Junction Temperature	Tj	°C		-55 ~ +175	

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	MBR10100CD	MBR10150CD	MBR10200CD
Maximum instantaneous forward voltage drop per diode	VFM	V	FM=5.0A	0.85	0.90	0.95
Maximum DC reverse current at rated DC blocking voltage per diode	RRM1	mA	VRM=VRRM Ta=25°C		0.1	
	RRM2		VRM=VRRM Ta=125°C		20	

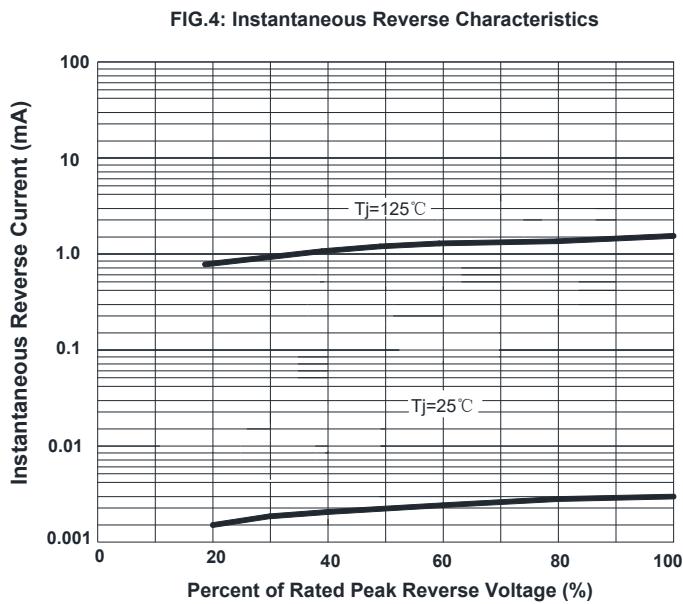
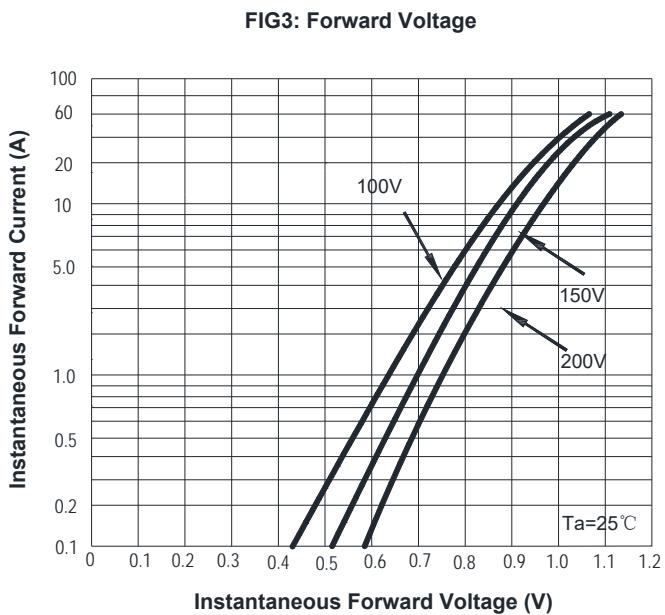
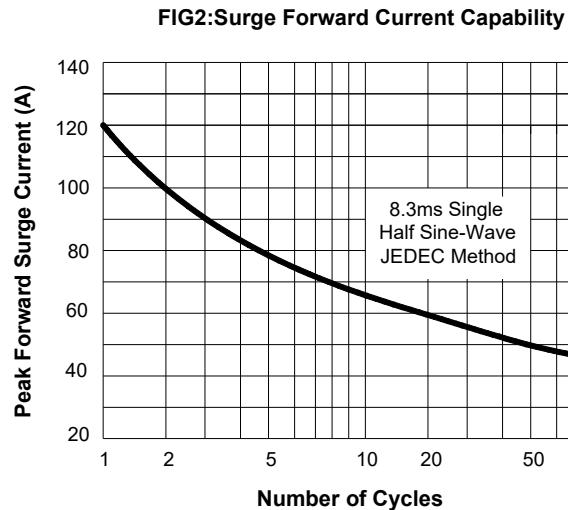
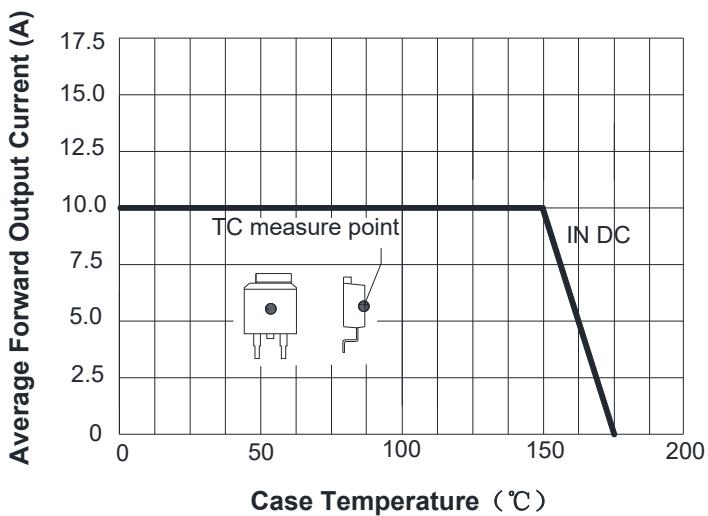
■Thermal Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	MBR10100CD	MBR10150CD	MBR10200CD
Thermal Resistance Between junction and case	RθJ-C	°C/W		5.0	

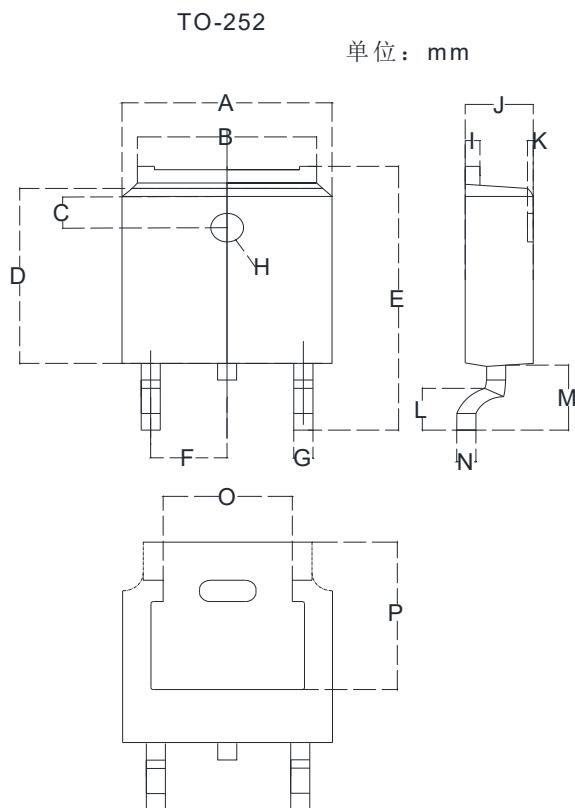
■Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MBR10100CD THRU MBR10200CD	Approximate 0.32	2500	2500	25000	Reel

■Characteristics (Typical)

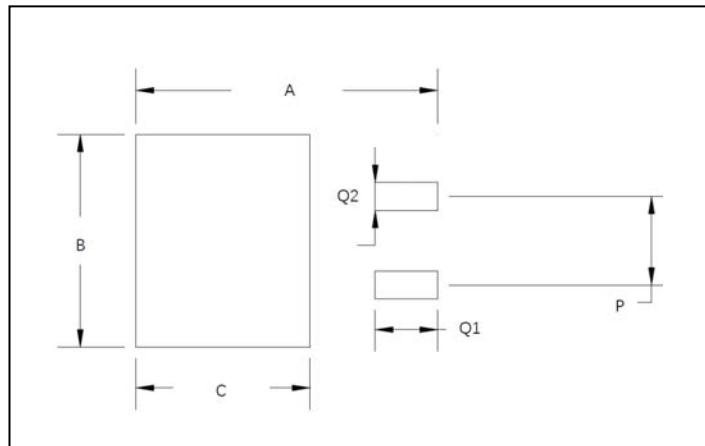


■ Outline Dimensions



TO-252		
Dim	Min	Max
A	6.500	6.700
B	5.100	5.460
C	1.400	1.800
D	6.000	6.200
E	10.000	10.400
F	2.166	2.366
G	0.660	0.860
H	Φ 1.050	Φ 1.350
I	0.460	0.580
J	2.200	2.400
K	0	0.300
L	0.890	2.290
M	2.730	3.080
N	0.430	0.580
O	4.2	4.95
P	5.15	5.45

■ Suggested Pad Layout



Dim	Millimeters
A	11.4
B	6.74
C	6.23
P	4.56
Q1	2.28
Q2	1.52